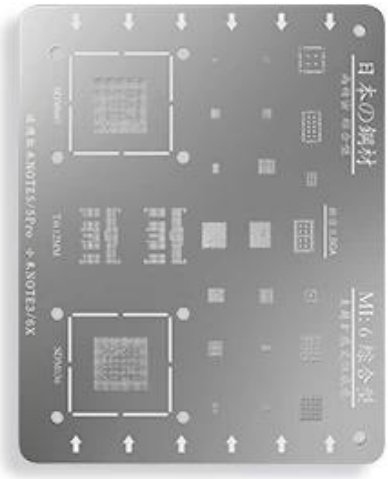
Description du produit

Convient pour iPhone / iPad
100% neuf et haute qualité
Remarque: il arrive que l'usine mette à jour le gabarit BGA Reballing, la taille peut être différente, mais la fonction est identique.

Product Usage



MATERIAL	Imported steel
BRAND	BESTOOL
PRODUCT NAME	Reballing Stencil
WEIGHT	7g
TYPE	Precise alignment Strong toughness Non-stick ti

▼CHARACTERISTICS

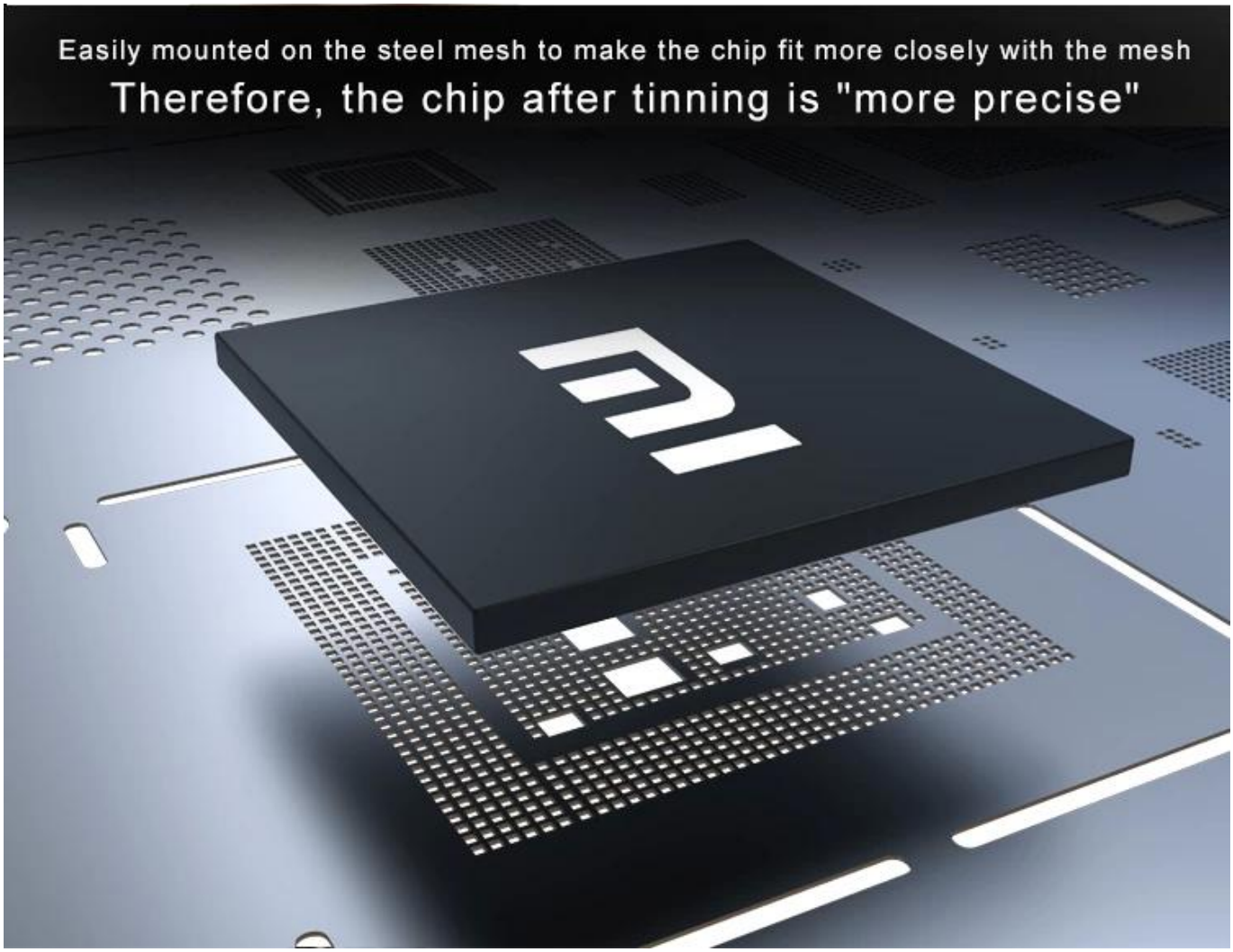
This product is used for BGA tinning repair of the REDMI/MI series. Imported steel, anti-rolling anti-deformation, automatic alignment, accurate hole position, non-stick tin, good toughness, good off-grid.

PRODUCT INFORMATION

IMPORTED STEEL

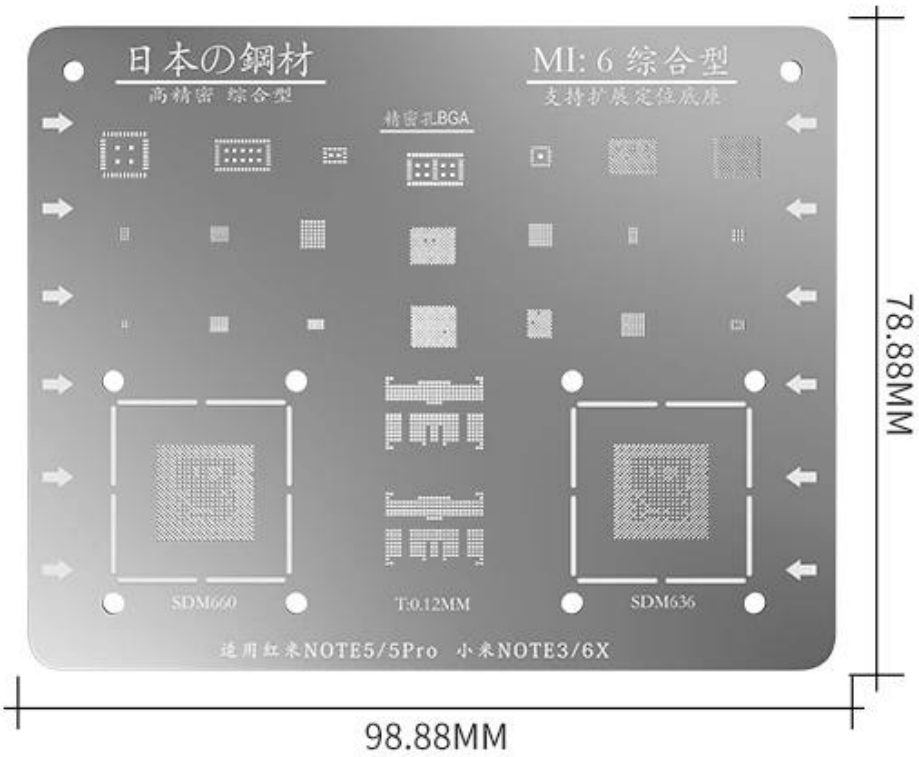
HIGH TOUGHNESS

GOOD PRODUCTS ARE NOT ONLY EXCELLENT FORGING PROCESSES, BUT THE REAL CORE LIES IN THE SELECTION OF DELICATE MATERIALS.


Easily mounted on the steel mesh to make the chip fit more closely with the mesh
Therefore, the chip after tinning is "more precise"

Imported steel
Hard and wear resistant
Accurate to the hole

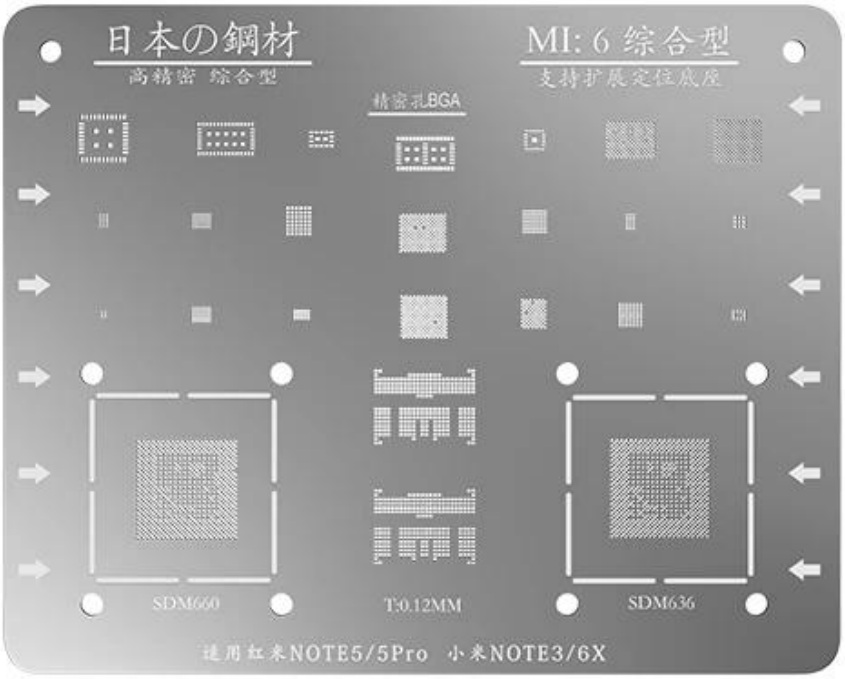
PRODUCT SIZE



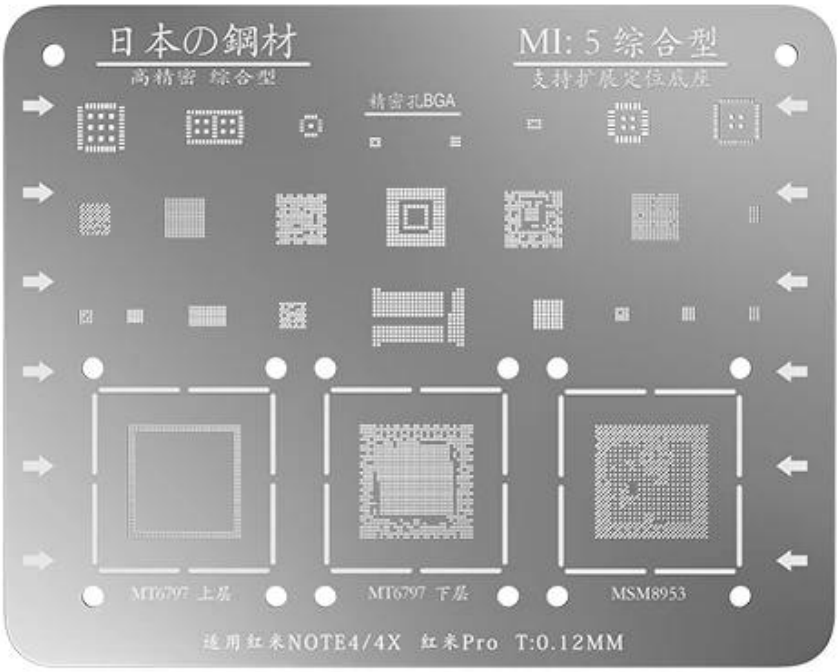
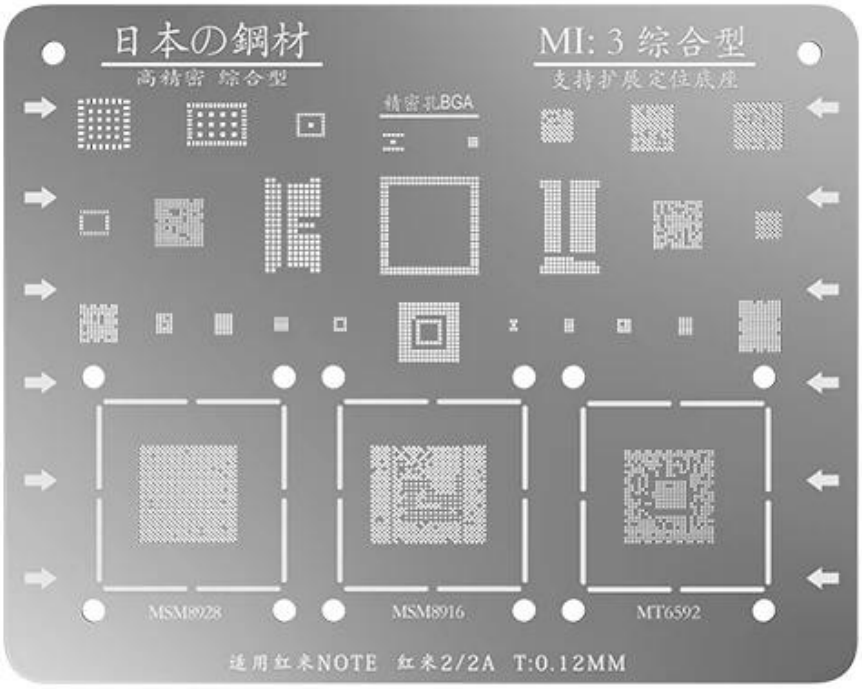
Thin to 0.12mm

Precise die-casting Iform heating

RED MI NOTE5/5Pro MI NOTE3/6X



BSTOOL RED MI NOTE4/4X RED MI Pro T:0.12MM



RED MI NOTE RED MI 2/2A T:0.12MM